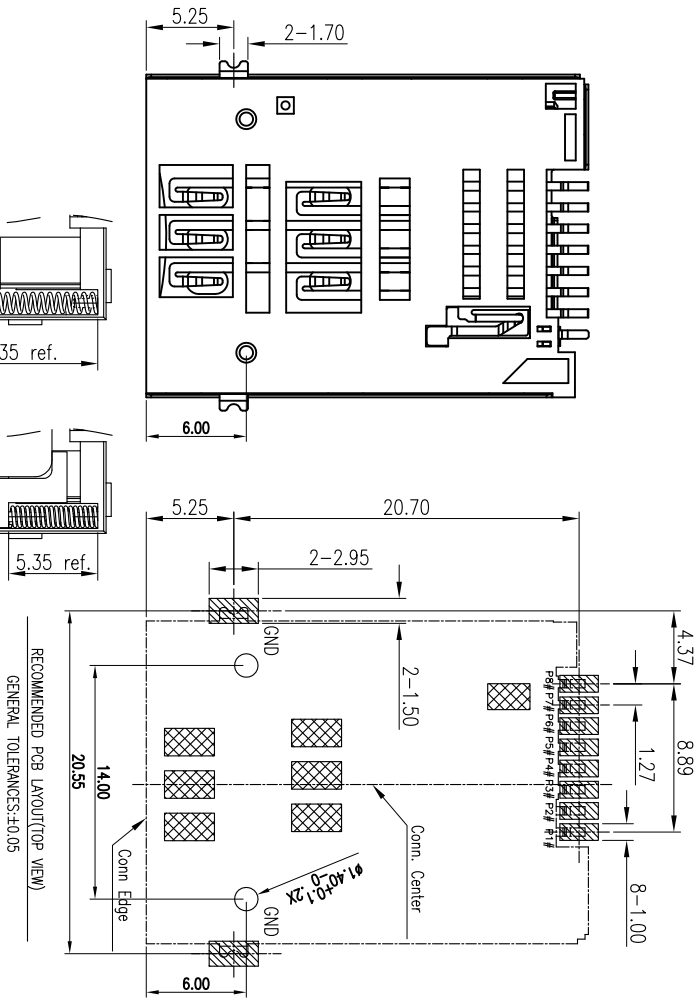
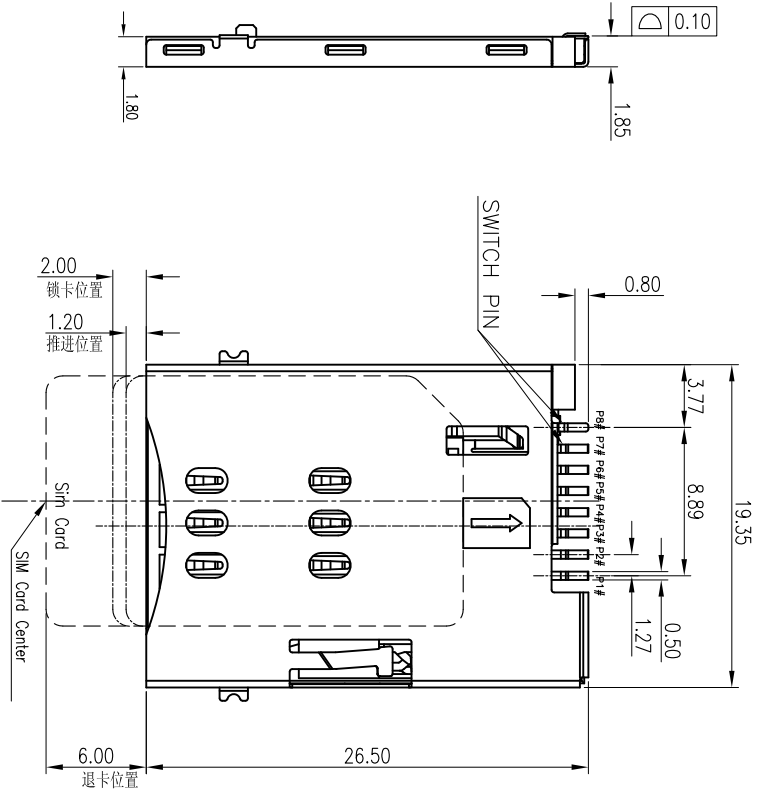


REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	2016.03.09			

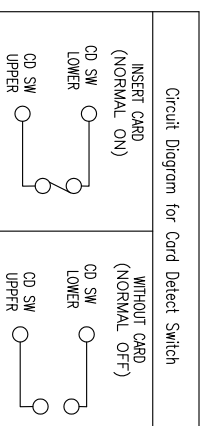


NOTES:
1) MATERIAL:
HOUSING: LCP UL 94V-0
CONTACT: C5210R-H-T=0.15
SHELL: SUS304 T=0.20
MYLAR: POLYESTER
2) FINISH:
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATING ON SOLDER TAILS, WITH
ENTIRE CONTACT UNDERPLATED 500µm. NICKEL
SHELL: 300µm. NICKEL UNDERPLATED OVERALL,
GOLD FLASH PLATED ON SOLDER TAILS
3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10

预压状态

工作状态

RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES: ±0.05
SOLDER AREA
NONE CIRCUIT DIAGRAM AREA



深圳市众新达电子有限公司

PART NUMBER: 102011312
TITLE: SIM card 6+2 pin push H1.8
(外壳厚度: 2.5mm, 有定位柱)

APPD: Segn
CHKD:
DWG NO.: A-102011312

QTY
SEE NOTES

DR: Yang

SCALE: 1:1
SHEET: 1
REV: A

MILLIMETERS	INCH	UNITS	MM
X° ± 2°	X° ± 2°	MAT'L	
X ± 0.30	.XX ± 0.012	SEE NOTES	
.XX ± 0.20	.XXX ± 0.008	FINISH	
.XXX ± 0.10	.XXXX ± 0.004	SEE NOTES	

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SIM 示意图
芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET